

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Kenichi FUNAMOTO et al. Serial No.: 09/395,179 Filing Date: September 14, 1999 For: PACKAGE FOR ELECTRONIC COMPONENT, LID MATERIAL FOR PACKAGE LID AND PRODUCTION METHOD FOR LID	Art Unit: 1775 Examiner: M. LaVilla  #21 Kw 21-04
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COMMENTARY RE INFORMATION DISCLOSURE STATEMENT

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

Dear Sir:

In accordance with 37 CFR §1.56, and in recognition of their duty to disclose to the United States Patent and Trademark Office relevant information known to be material to patentability, Applicants herewith submit a copy of an Office Action received from the European Patent Office in the European Patent Application corresponding to the above-identified U.S. Patent Application, which is listed on the attached Information Disclosure Statement (Form PTO-1449). This statement is not a representation that all of the information cited is necessarily effective as prior art against the application.

Applicants respectfully request that the disclosed reference be made of record in the subject application.

Respectfully submitted,



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Date: June 19, 2002

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